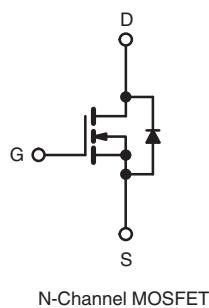
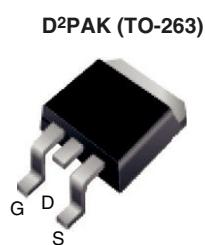


## D Series Power MOSFET

PRODUCT SUMMARY	
$V_{DS}$ (V) at $T_J$ max.	550
$R_{DS(on)}$ max. at 25 °C (Ω)	$V_{GS} = 10$ V 0.85
$Q_g$ (max.) (nC)	30
$Q_{gs}$ (nC)	4
$Q_{gd}$ (nC)	7
Configuration	Single



### ORDERING INFORMATION

Package	D <sup>2</sup> PAK (TO-263)
Lead (Pb)-free and Halogen-free	SiHB8N50D-GE3

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			$V_{DS}$	500	V
Gate-Source Voltage			$V_{GS}$	$\pm 30$	
Gate-Source Voltage AC ( $f > 1$ Hz)				30	
Continuous Drain Current ( $T_J = 150$ °C)	$V_{GS}$ at 10 V		$I_D$	8.7	A
				5.5	
Pulsed Drain Current <sup>a</sup>			$I_{DM}$	18	
Linear Derating Factor				1.25	W/°C
Single Pulse Avalanche Energy <sup>b</sup>			$E_{AS}$	29	mJ
Maximum Power Dissipation			$P_D$	156	W
Operating Junction and Storage Temperature Range			$T_J, T_{stg}$	- 55 to + 150	°C
Drain-Source Voltage Slope	$T_J = 125$ °C		$dV/dt$	24	V/ns
Reverse Diode $dV/dt^d$				0.37	
Soldering Recommendations (Peak Temperature) <sup>c</sup>	for 10 s			300	°C

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD} = 50$  V, starting  $T_J = 25$  °C,  $L = 2.3$  mH,  $R_g = 25$  Ω,  $I_{AS} = 5$  A.
- c. 1.6 mm from case.
- d.  $I_{SD} \leq I_D$ , starting  $T_J = 25$  °C.



RoHS  
COMPLIANT  
HALOGEN  
FREE

### FEATURES

- Optimal Design
  - Low Area Specific On-Resistance
  - Low Input Capacitance ( $C_{iss}$ )
  - Reduced Capacitive Switching Losses
  - High Body Diode Ruggedness
  - Avalanche Energy Rated (UIS)
- Optimal Efficiency and Operation
  - Low Cost
  - Simple Gate Drive Circuitry
  - Low Figure-of-Merit (FOM):  $R_{on} \times Q_g$
  - Fast Switching
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

### APPLICATIONS

- Consumer Electronics
  - Displays (LCD or Plasma TV)
- Server and Telecom Power Supplies
  - SMPS
- Industrial
  - Welding
  - Induction Heating
  - Motor Drives
- Battery Chargers

**THERMAL RESISTANCE RATINGS**

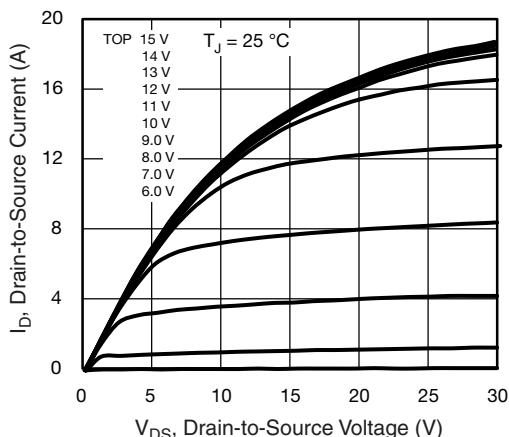
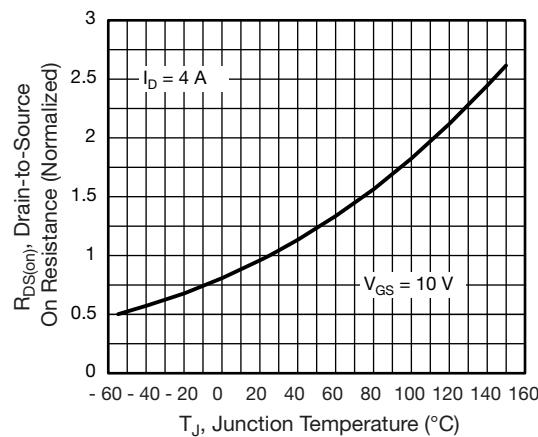
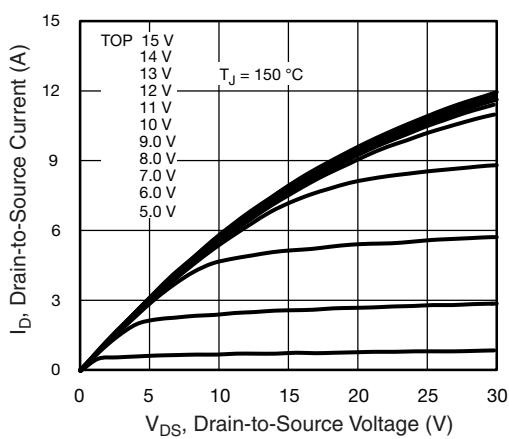
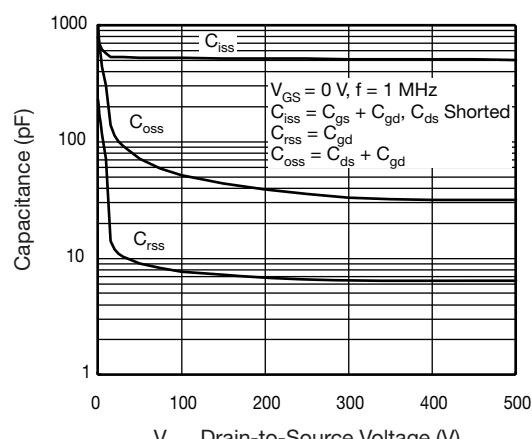
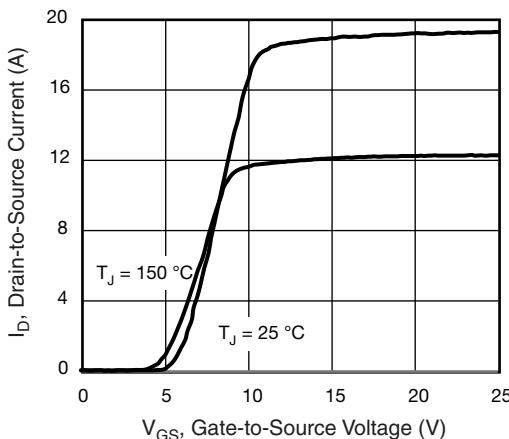
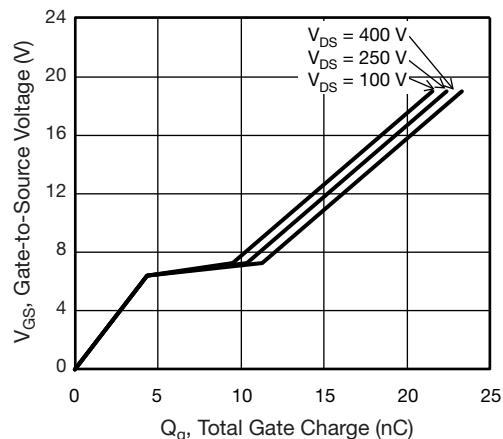
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	°C/W
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.8	

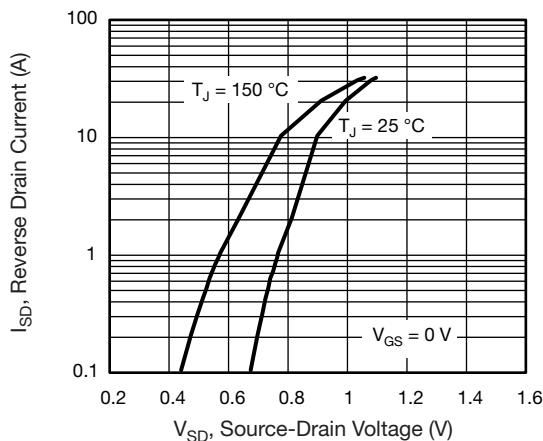
**SPECIFICATIONS (T<sub>J</sub> = 25 °C, unless otherwise noted)**

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
<b>Static</b>								
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}$	$I_D = 250 \mu\text{A}$	500	-	-	V	
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, $I_D = 250 \mu\text{A}$		-	0.58	-	V/°C	
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}$	$I_D = 250 \mu\text{A}$	3	-	5	V	
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30 \text{ V}$		-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 500 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	-	1	μA	
		$V_{DS} = 400 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 125 \text{ °C}$		-	-	10		
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 4 \text{ A}$	-	0.70	0.85	Ω	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 20 \text{ V}$ , $I_D = 4 \text{ A}$		-	3	-	S	
<b>Dynamic</b>								
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 100 \text{ V}$ , $f = 1 \text{ MHz}$		-	527	-	pF	
Output Capacitance	$C_{oss}$			-	52	-		
Reverse Transfer Capacitance	$C_{rss}$			-	8	-		
Effective Output Capacitance, Energy Related <sup>b</sup>	$C_{o(er)}$	$V_{DS} = 0 \text{ V to } 400 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	46	-		
Effective Output Capacitance, Time Related <sup>c</sup>	$C_{o(tr)}$			-	64	-		
Total Gate Charge	$Q_g$	$V_{GS} = 10 \text{ V}$	$I_D = 4 \text{ A}$ , $V_{DS} = 400 \text{ V}$	-	15	30	nC	
Gate-Source Charge	$Q_{gs}$			-	4	-		
Gate-Drain Charge	$Q_{gd}$			-	7	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 400 \text{ V}$ , $I_D = 4 \text{ A}$ $R_g = 9.1 \Omega$ , $V_{GS} = 10 \text{ V}$		-	13	26	ns	
Rise Time	$t_r$			-	16	32		
Turn-Off Delay Time	$t_{d(off)}$			-	17	34		
Fall Time	$t_f$			-	11	22		
Gate Input Resistance	$R_g$	$f = 1 \text{ MHz}$ , open drain		-	1.8	-	Ω	
<b>Drain-Source Body Diode Characteristics</b>								
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	8	A	
Pulsed Diode Forward Current	$I_{SM}$			-	-	32		
Diode Forward Voltage	$V_{SD}$	$T_J = 25 \text{ °C}$ , $I_S = 4 \text{ A}$ , $V_{GS} = 0 \text{ V}$		-	-	1.2	V	
Reverse Recovery Time	$t_{rr}$	$T_J = 25 \text{ °C}$ , $I_F = I_S = 4 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_R = 20 \text{ V}$		-	308	-	ns	
Reverse Recovery Charge	$Q_{rr}$			-	1.8	-		
Reverse Recovery Current	$I_{RRM}$			-	11	-	A	

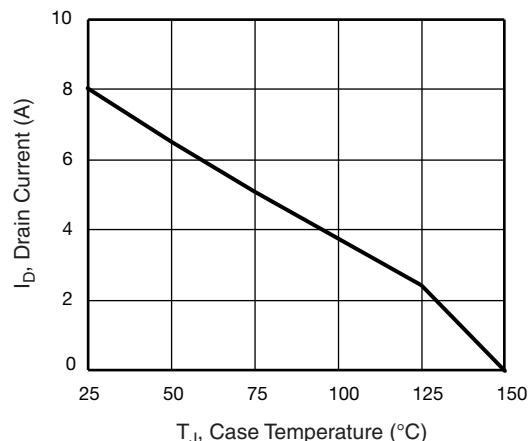
**Notes**

- Repetitive rating; pulse width limited by maximum junction temperature.
- $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .
- $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

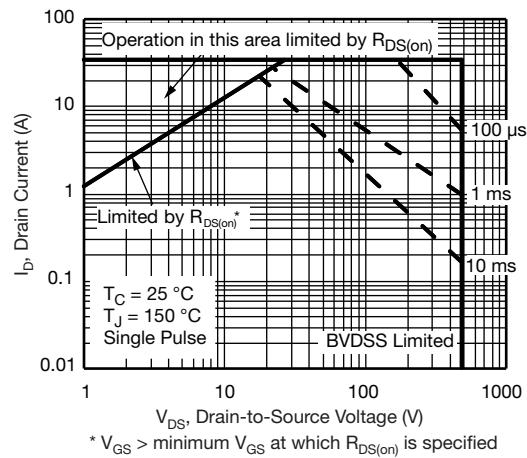
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



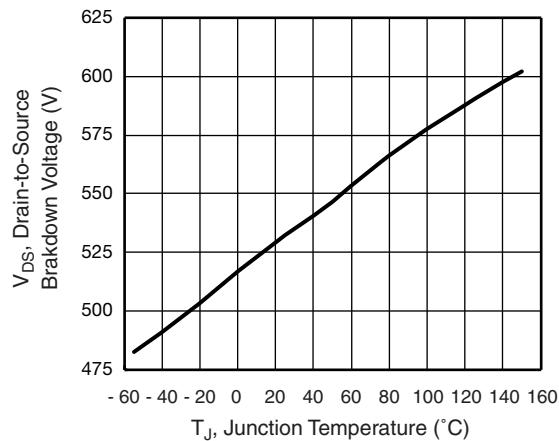
**Fig. 7 - Typical Source-Drain Diode Forward Voltage**



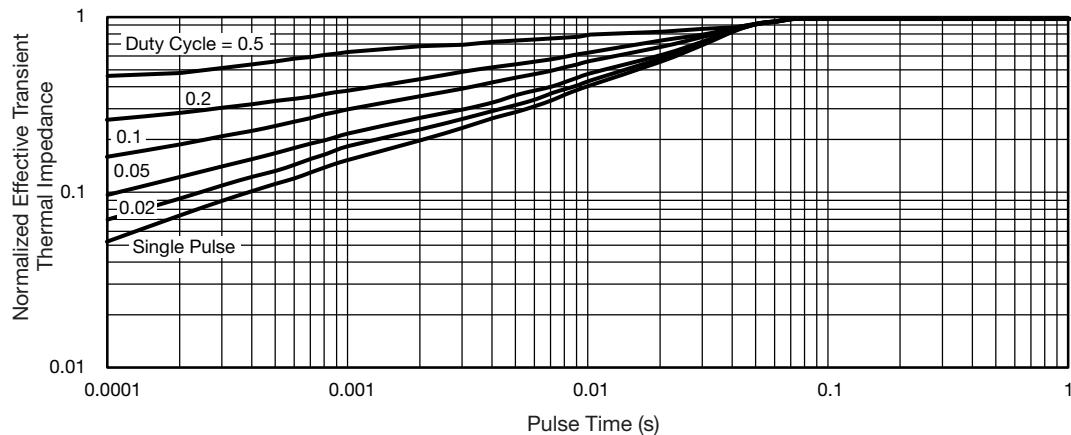
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



**Fig. 8 - Maximum Safe Operating Area**



**Fig. 10 - Typical Drain-to-Source Voltage vs. Temperature**



**Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case**

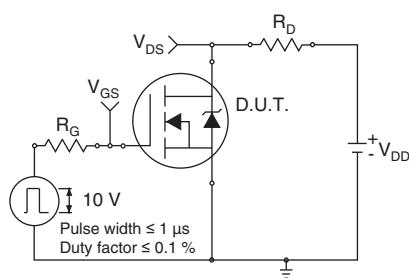


Fig. 12 - Switching Time Test Circuit

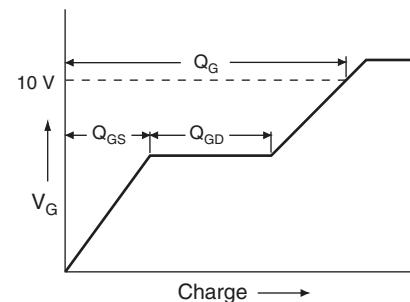


Fig. 16 - Basic Gate Charge Waveform

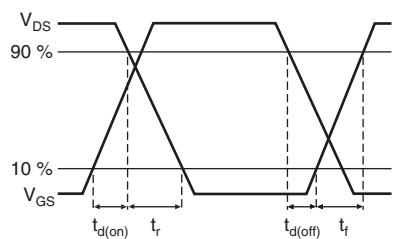


Fig. 13 - Switching Time Waveforms

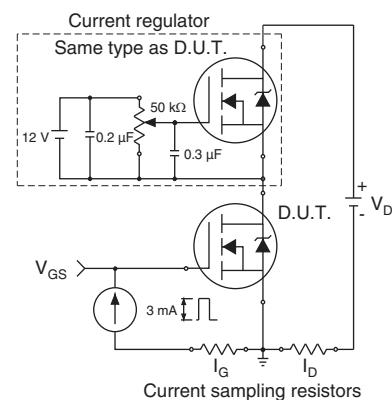


Fig. 17 - Gate Charge Test Circuit

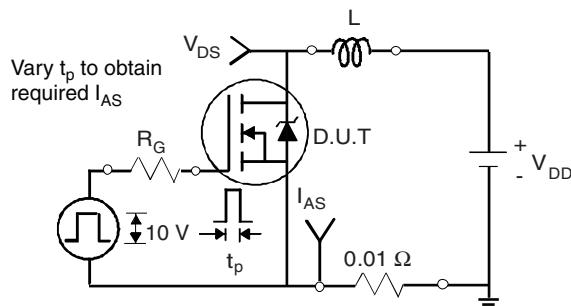


Fig. 14 - Unclamped Inductive Test Circuit

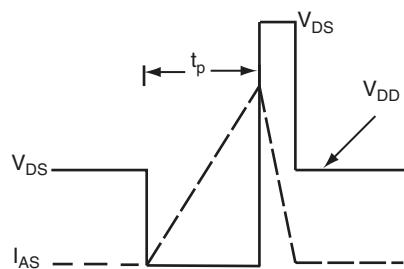
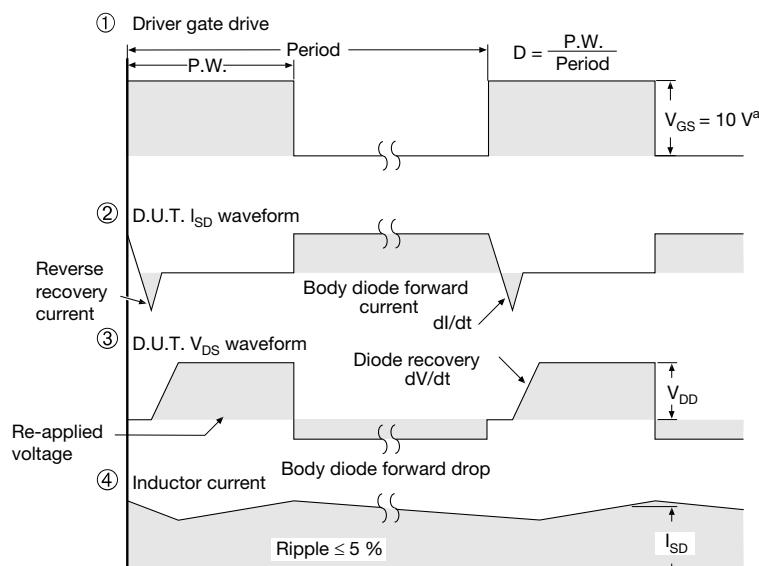
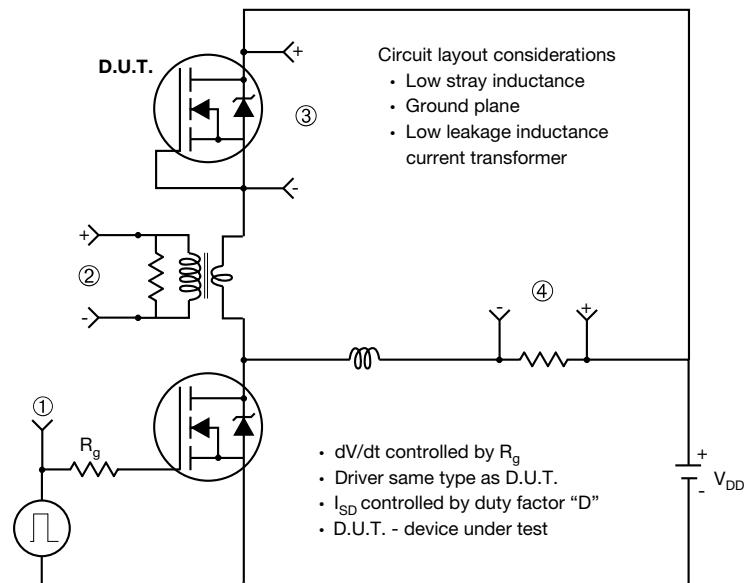


Fig. 15 - Unclamped Inductive Waveforms

**Peak Diode Recovery  $dV/dt$  Test Circuit**


**Note**  
a.  $V_{GS} = 5 \text{ V}$  for logic level devices

**Fig. 18 - For N-Channel**

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